



# STPS3045CT/CG/CR/CP/CPI/CW/CFP

## POWER SCHOTTKY RECTIFIER

### MAIN PRODUCT CHARACTERISTICS

$I_{F(AV)}$	2 x 15 A
$V_{RMM}$	45 V
$T_j$ (max)	175 °C
$V_F$	0.57 V

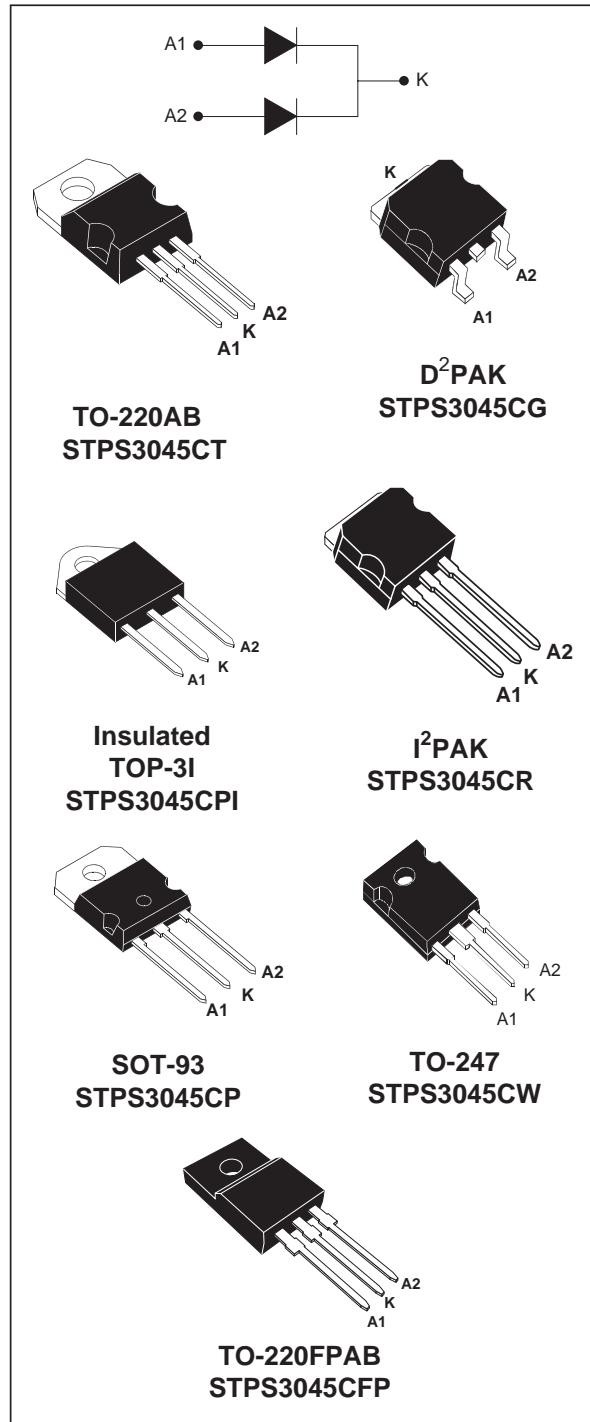
### FEATURES AND BENEFITS

- VERY SMALL CONDUCTION LOSSES
- NEGLIGIBLE SWITCHING LOSSES
- EXTREMELY FAST SWITCHING
- LOW THERMAL RESISTANCE
- INSULATED PACKAGE: TOP-3I  
Insulating voltage = 2500V RMS  
Capacitance = 12pF
- AVALANCHE CAPABILITY SPECIFIED

### DESCRIPTION

Dual center tap Schottky rectifier suited for SwitchMode Power Supply and high frequency DC to DC converters.

Packaged either in TO-220AB, TO-220FPAB, D<sup>2</sup>PAK, I<sup>2</sup>PAK, TO-247, SOT93 or TOP-3I, this device is especially intended for use in low voltage, high frequency inverters, free wheeling and polarity protection applications.



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### ABSOLUTE RATINGS (limiting values, per diode)

Symbol	Parameter				Value	Unit
V <sub>RRM</sub>	Repetitive peak reverse voltage				45	V
I <sub>F(RMS)</sub>	RMS forward current				30	A
I <sub>F(AV)</sub>	Average forward current $\delta = 0.5$	TO-220AB / D <sup>2</sup> PAK / I <sup>2</sup> PAK / SOT-93 / TO-247	T <sub>c</sub> = 155°C	Per diode Per device	15	A
		TO-220FPAB	T <sub>c</sub> = 130°C		30	
		TOP-3I	T <sub>c</sub> = 150°C			
I <sub>FSM</sub>	Surge non repetitive forward current		t <sub>p</sub> = 10 ms sinusoidal	220		A
I <sub>RRM</sub>	Repetitive peak reverse current		t <sub>p</sub> = 2 $\mu$ s square F = 1kHz	1		A
I <sub>RSM</sub>	Non repetitive peak reverse current		t <sub>p</sub> = 100 $\mu$ s square	3		A
P <sub>ARM</sub>	Repetitive peak avalanche power		t <sub>p</sub> = 1 $\mu$ s T <sub>j</sub> = 25°C	6000		W
T <sub>stg</sub>	Storage temperature range			-65 to +175		°C
T <sub>j</sub>	Maximum operating junction temperature *			175		°C
dV/dt	Critical rate of rise of reverse voltage			10000		V/ $\mu$ s

\* :  $\frac{dP_{tot}}{dT_j} < \frac{1}{R_{th}(j-a)}$  thermal runaway condition for a diode on its own heatsink

### THERMAL RESISTANCES

Symbol	Parameter			Value	Unit
R <sub>th(j-c)</sub>	Junction to case	TO-220AB / D <sup>2</sup> PAK / I <sup>2</sup> PAK	Per diode	1.60	°C/W
			Total	0.85	
		SOT-93 / TO-247	Per diode	1.5	
			Total	0.8	
R <sub>th(c)</sub>		TO-220FPAB	Per diode	4	
			Total	3.2	
		TOP-3I	Per diode	2.2	
			Total	1.6	
		TO-220AB / D <sup>2</sup> PAK / I <sup>2</sup> PAK SOT-93 / TO-247	Coupling	0.10	
		TO-220FPAB	Coupling	2.5	
		TOP-3I	Coupling	1.0	

When the diodes 1 and 2 are used simultaneously:

$$\Delta T_j \text{ (diode 1)} = P \text{ (diode1)} \times R_{th(j-c)} \text{ (per diode)} + P \text{ (diode 2)} \times R_{th(c)}$$

### STATIC ELECTRICAL CHARACTERISTICS (Per diode)

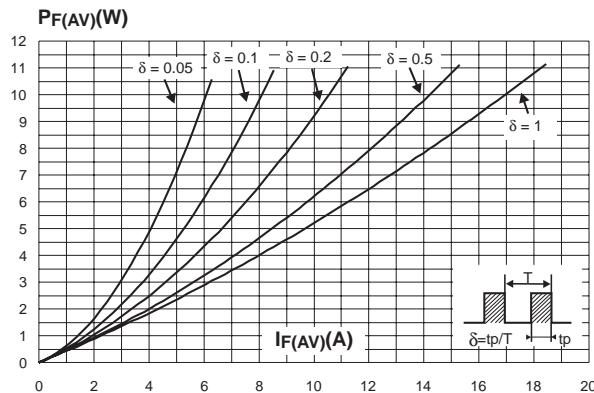
Symbol	Parameter	Tests Conditions		Min.	Typ.	Max.	Unit
I <sub>R</sub> *	Reverse leakage current	T <sub>j</sub> = 25°C	V <sub>R</sub> = V <sub>RRM</sub>			200	$\mu$ A
		T <sub>j</sub> = 125°C			11	40	mA
V <sub>F</sub> *	Forward voltage drop	T <sub>j</sub> = 125°C	I <sub>F</sub> = 15 A		0.5	0.57	V
		T <sub>j</sub> = 25°C	I <sub>F</sub> = 30 A			0.84	
		T <sub>j</sub> = 125°C	I <sub>F</sub> = 30 A		0.65	0.72	

Pulse test : \* tp = 380  $\mu$ s,  $\delta < 2\%$

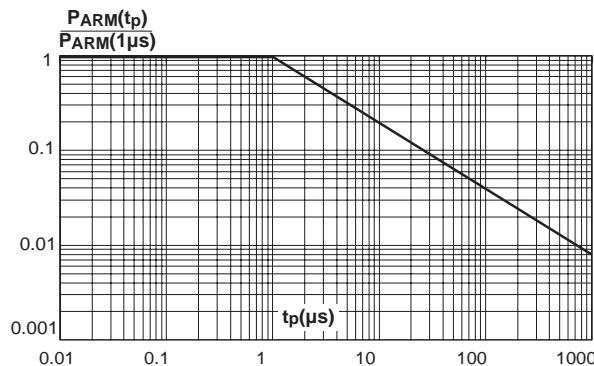
To evaluate the conduction losses use the following equation :

$$P = 0.42 \times I_{F(AV)} + 0.01 I_{F(RMS)}^2$$

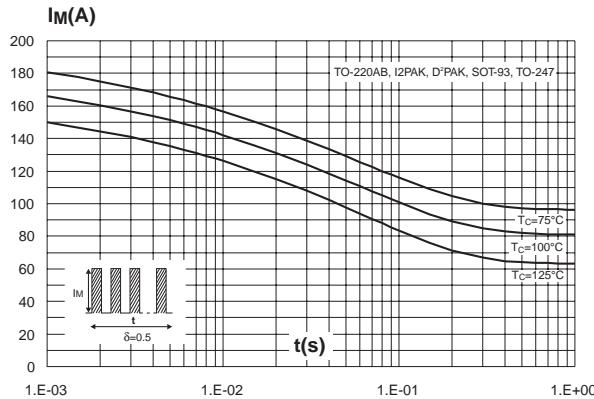
**Fig. 1:** Average forward power dissipation versus average forward current (per diode).



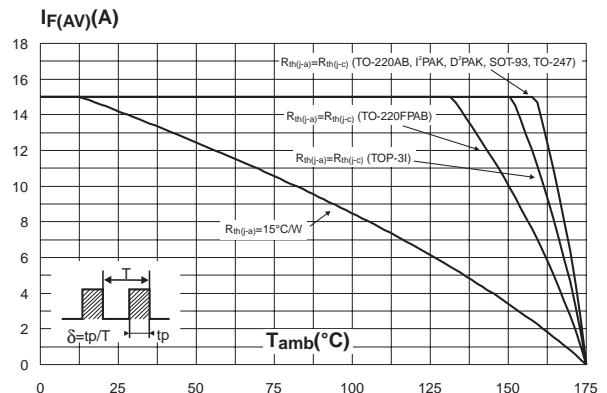
**Fig. 3:** Normalized avalanche power derating versus pulse duration.



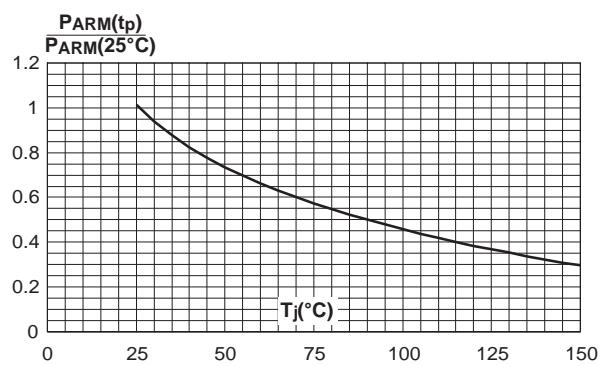
**Fig. 5-1:** Non repetitive surge peak forward current versus overload duration (maximum values, per diode).



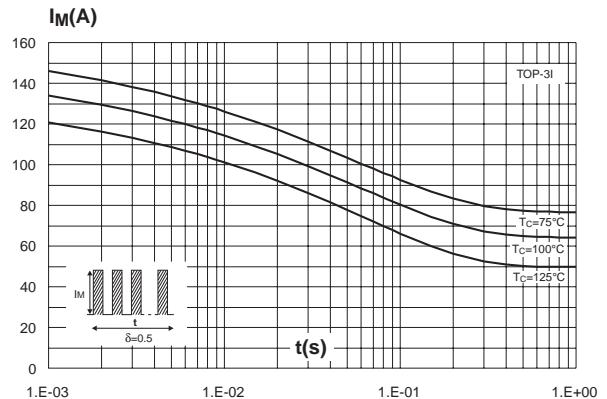
**Fig. 2:** Average current versus ambient temperature ( $\delta = 0.5$ , per diode).



**Fig. 4:** Normalized avalanche power derating versus junction temperature.

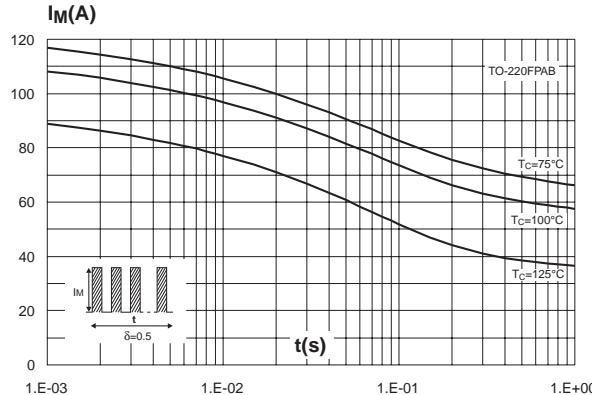


**Fig. 5-2:** Non repetitive surge peak forward current versus overload duration (maximum values, per diode).

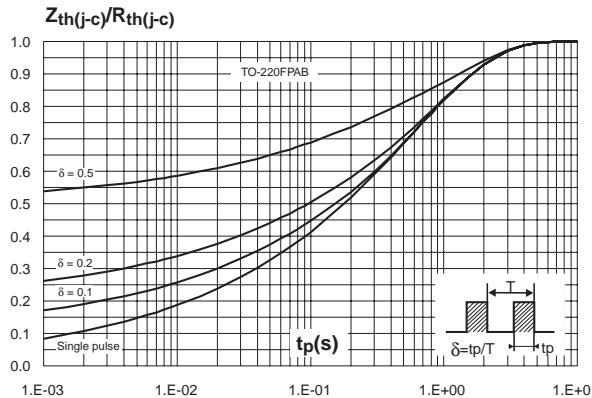


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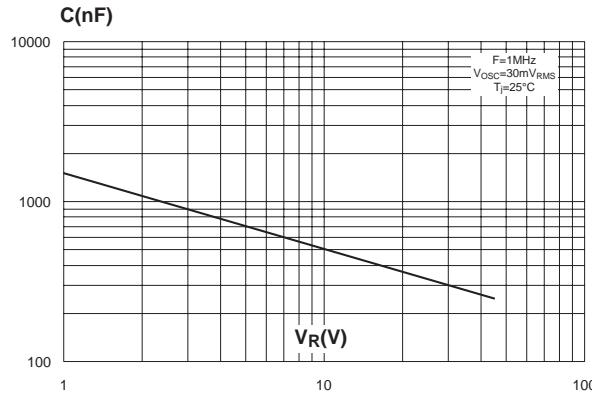
**Fig. 5-3:** Non repetitive surge peak forward current versus overload duration (maximum values, per diode).



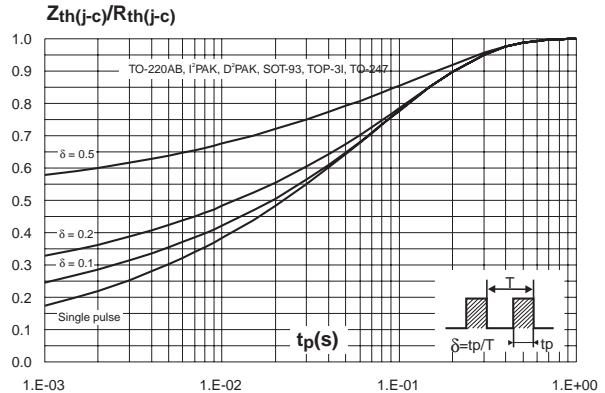
**Fig. 6-2:** Relative variation of thermal transient impedance junction to case versus pulse duration.



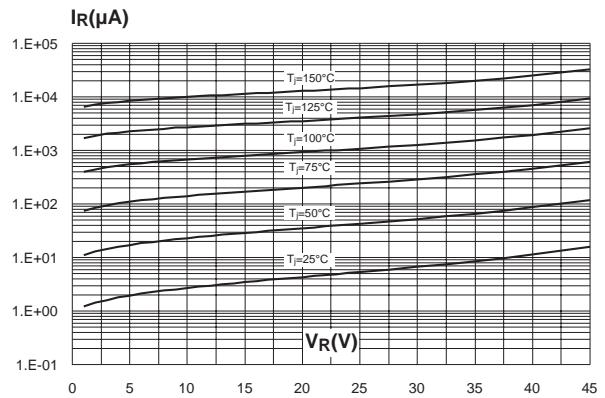
**Fig. 8:** Junction capacitance versus reverse voltage applied (typical values, per diode).



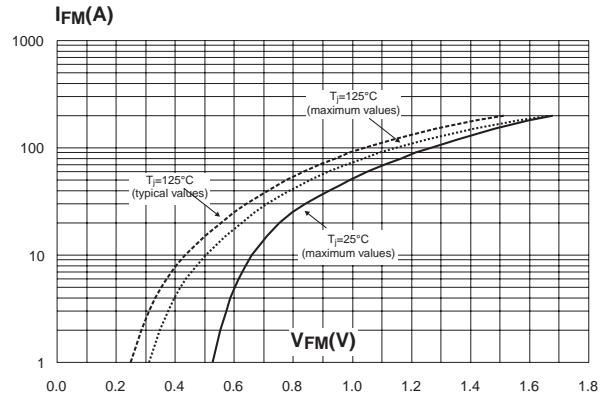
**Fig. 6-1:** Relative variation of thermal transient impedance junction to case versus pulse duration.



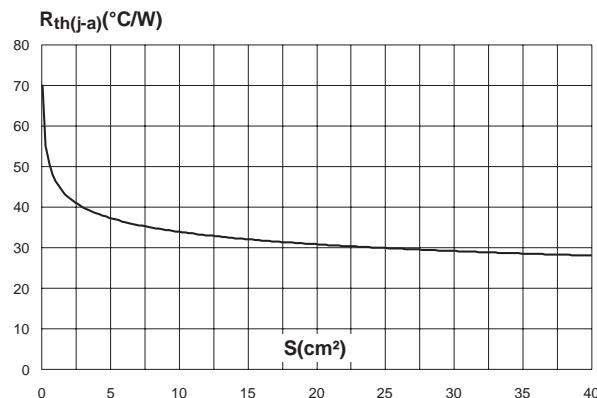
**Fig. 7:** Reverse leakage current versus reverse voltage applied (typical values, per diode).



**Fig. 9:** Forward voltage drop versus forward current (maximum values, per diode).



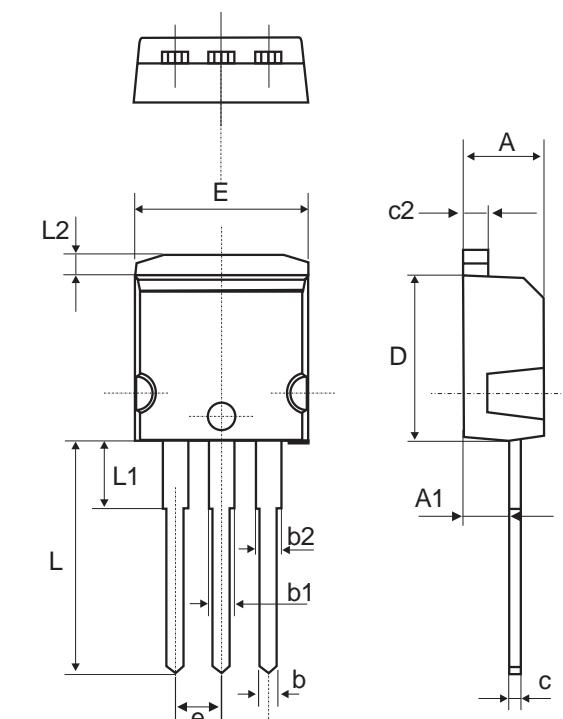
**Fig. 10:** Thermal resistance junction to ambient versus copper surface under tab (epoxy printed board FR4, Cu=35 $\mu$ m).



**PACKAGE MECHANICAL DATA**  
TO-220AB

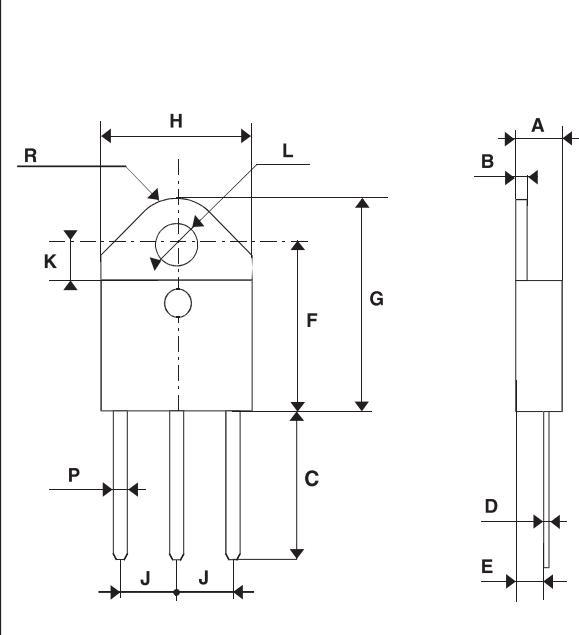
REF.	DIMENSIONS			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.40	4.60	0.173	0.181
C	1.23	1.32	0.048	0.051
D	2.40	2.72	0.094	0.107
E	0.49	0.70	0.019	0.027
F	0.61	0.88	0.024	0.034
F1	1.14	1.70	0.044	0.066
F2	1.14	1.70	0.044	0.066
G	4.95	5.15	0.194	0.202
G1	2.40	2.70	0.094	0.106
H2	10	10.40	0.393	0.409
L2	16.4 typ.		0.645 typ.	
L4	13	14	0.511	0.551
L5	2.65	2.95	0.104	0.116
L6	15.25	15.75	0.600	0.620
L7	6.20	6.60	0.244	0.259
L9	3.50	3.93	0.137	0.154
M	2.6 typ.		0.102 typ.	
Diam.	3.75	3.85	0.147	0.151

**PACKAGE MECHANICAL DATA**  
I<sup>2</sup>PAK

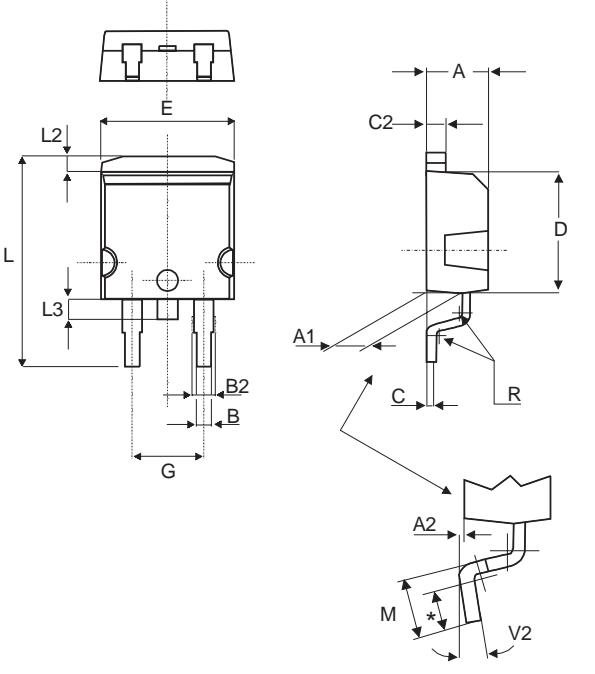


REF.	DIMENSIONS			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.40	4.60	0.173	0.181
A1	2.49	2.69	0.098	0.106
b	0.70	0.93	0.028	0.037
b1	1.14	1.17	0.044	0.046
b2	1.14	1.17	0.044	0.046
c	0.45	0.60	0.018	0.024
c2	1.23	1.36	0.048	0.054
D	8.95	9.35	0.352	0.368
e	2.40	2.70	0.094	0.106
E	10.0	10.4	0.394	0.409
L	13.1	13.6	0.516	0.535
L1	3.48	3.78	0.137	0.149
L2	1.27	1.40	0.050	0.055

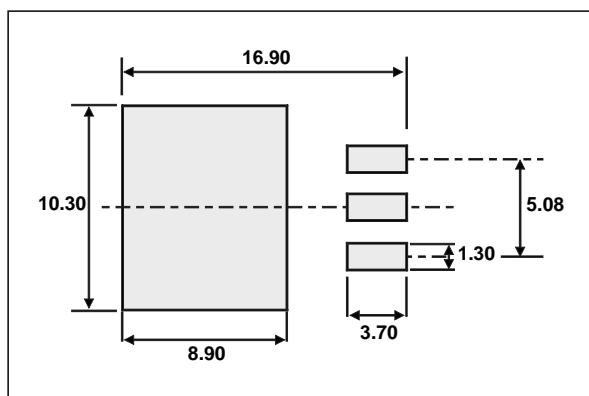
**PACKAGE MECHANICAL DATA**  
TOP-31 (isolated)



REF.	DIMENSIONS					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	4.4			4.6	0.173	
B	1.45			1.55	0.057	
C	14.35			15.60	0.565	
D	0.5			0.7	0.020	
E	2.7			2.9	0.106	
F	15.8			16.5	0.622	
G	20.4			21.1	0.815	
H	15.1			15.5	0.594	
J	5.4			5.65	0.213	
K	3.4			3.65	0.134	
L	4.08			4.17	0.161	
P	1.20			1.40	0.047	
R		4.60			0.181	

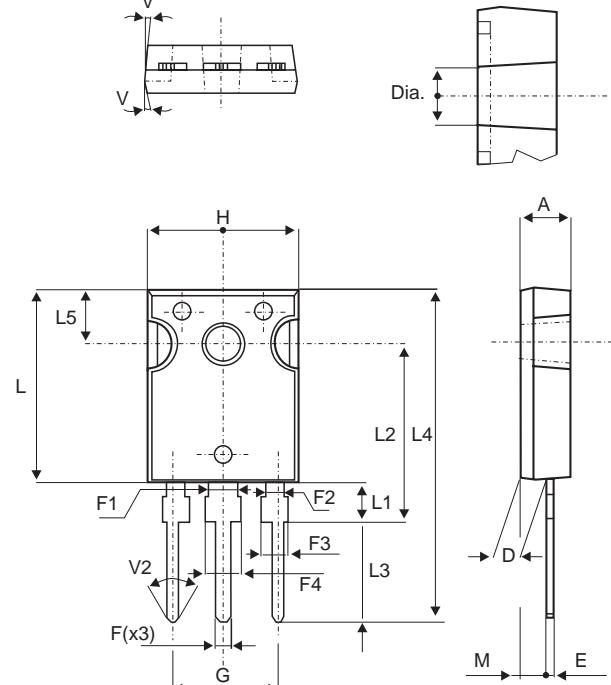
**PACKAGE MECHANICAL DATA**  
**D<sup>2</sup>PAK**


REF.	DIMENSIONS			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.40	4.60	0.173	0.181
A1	2.49	2.69	0.098	0.106
A2	0.03	0.23	0.001	0.009
B	0.70	0.93	0.027	0.037
B2	1.14	1.70	0.045	0.067
C	0.45	0.60	0.017	0.024
C2	1.23	1.36	0.048	0.054
D	8.95	9.35	0.352	0.368
E	10.00	10.40	0.393	0.409
G	4.88	5.28	0.192	0.208
L	15.00	15.85	0.590	0.624
L2	1.27	1.40	0.050	0.055
L3	1.40	1.75	0.055	0.069
M	2.40	3.20	0.094	0.126
R	0.40 typ.		0.016 typ.	
V2	0°	8°	0°	8°

**FOOTPRINT DIMENSIONS** (in millimeters)


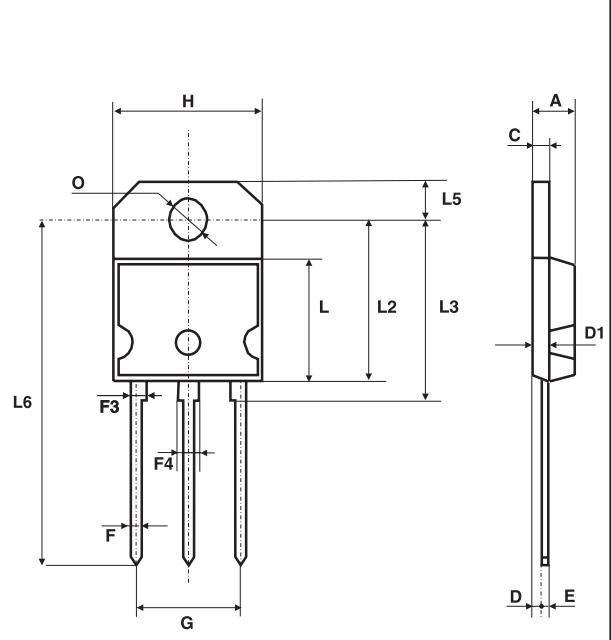
## STPS3045CT/CG/CR/CP/CPI/CW/CFP

### PACKAGE MECHANICAL DATA TO-247



REF.	DIMENSIONS					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	4.85		5.15	0.191		0.203
D	2.20		2.60	0.086		0.102
E	0.40		0.80	0.015		0.031
F	1.00		1.40	0.039		0.055
F1		3.00			0.118	
F2		2.00			0.078	
F3	2.00		2.40	0.078		0.094
F4	3.00		3.40	0.118		0.133
G		10.90			0.429	
H	15.45		15.75	0.608		0.620
L	19.85		20.15	0.781		0.793
L1	3.70		4.30	0.145		0.169
L2		18.50			0.728	
L3	14.20		14.80	0.559		0.582
L4		34.60			1.362	
L5		5.50			0.216	
M	2.00		3.00	0.078		0.118
V		5°			5°	
V2		60°			60°	
Dia.	3.55		3.65	0.139		0.143

### PACKAGE MECHANICAL DATA SOT-93



REF.	DIMENSIONS					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	4.70		4.90	0.185		0.193
C	1.90		2.10	0.075		0.083
D		2.50			0.098	
D1		2.00			0.078	
E	0.50		0.78	0.020		0.031
F	1.10		1.30	0.043		0.051
F3		1.75			0.069	
F4		2.10			0.083	
G	10.80		11.10	0.425		0.437
H	14.70		15.20	0.279		0.598
L		12.20			0.480	
L2		16.20			0.638	
L3		18.0			0.709	
L5	3.95		4.15	0.156		0.163
L6		31.00			1.220	
O	4.00		4.10	0.157		0.161

**PACKAGE MECHANICAL DATA**  
TO-220FPAB

REF.	DIMENSIONS			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.4	4.6	0.173	0.181
B	2.5	2.7	0.098	0.106
D	2.5	2.75	0.098	0.108
E	0.45	0.70	0.018	0.027
F	0.75	1	0.030	0.039
F1	1.15	1.70	0.045	0.067
F2	1.15	1.70	0.045	0.067
G	4.95	5.20	0.195	0.205
G1	2.4	2.7	0.094	0.106
H	10	10.4	0.393	0.409
L2	16 Typ.		0.63 Typ.	
L3	28.6	30.6	1.126	1.205
L4	9.8	10.6	0.386	0.417
L5	2.9	3.6	0.114	0.142
L6	15.9	16.4	0.626	0.646
L7	9.00	9.30	0.354	0.366
Dia.	3.00	3.20	0.118	0.126

Type	Marking	Package	Weight	Base qty	Delivery mode
STPS3045CT	STPS3045CT	TO-220AB	2.23 g.	50	Tube
STPS3045CG	STPS3045CG	D <sup>2</sup> PAK	1.48 g.	50	Tube
STPS3045CG-TR	STPS3045CG	D <sup>2</sup> PAK	1.48 g.	1000	Tape & reel
STPS3045CR	STPS3045CR	I <sup>2</sup> PAK	1.48 g	50	Tube
STPS3045CP	STPS3045CP	SOT-93	3.97 g.	30	Tube
STPS3045CPI	STPS3045CPI	TOP-3I	4.46 g.	120	Bulk
STPS3045CW	STPS3045CW	TO-247	4.46 g.	30	Tube
STPS3045CFP	STPS3045CFP	TO-220FPAB	2.0 g.	50	Tube

- Cooling method: by conduction (C)
- Recommended torque value (SOT-93, TOP-3I, TO-247): 0.8 N.m.
- Recommended torque value (TO-220AB): 0.55 N.m.
- Maximum torque value (SOT-93, TOP-3I, TO-247): 1.0 N.m.
- Maximum torque value (TO-220AB): 0.7 N.m.

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